



JRW
PATENT
8038-1011-2

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of

Koichi OHTO Conf. 4540

Application No. 10/622,645 Group 2813

Filed July 21, 2003 Examiner E. Kielin

METHOD FOR FORMING A CAPPING LAYER
ON A COPPER INTERCONNECT

SUPPLEMENTAL AMENDMENT

Assistant Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

April 14, 2005

Sir:

Supplemental to the response filed on April 6, 2005,
please further amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing
of claims which begins on page 2 of this paper.

Remarks begin on page 4 of this paper.